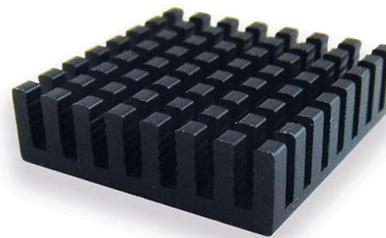


# Product Data Sheet Type: PG2828/8/SE/SF

Group: HEATSINKS Board Level

For single mounting

Width : 28 mm  
Height : 8 mm  
Length : 28 mm  
Minimum thermal resistance : 11 K/W  
For device : PGA|BGA|IC  
Device mounted by :  
Heatsink mounted by :  
Surface :  
Material : AlMgSi0,5



- Heatsinks for microprocessors (Extrusion Technology)
- Direct mounting with self-adhesive foil
- Best possible heat radiation from black anodized surface
- RthKvalues apply to natural convection (without external ventilation)
- Arrangement and number of pins for optimal air flow
- Even heat distribution in the base and the pins in the direction of heat flow
- Suitable for forced and free convection
- Aluminium alloy Al MgSi 0.5
- Thermal conductivity: 180-200 W / mK
- Other dimensions and surface finishes by request

